



RFS-100

PINLESS WELDING SYSTEM FOR FLEX AND RIGID-FLEX

Precise Visual Lay-Up, Alignment & Bonding of Multilayers

The RFS -100 Optical Registration System allows for pinless lamination of multilayers, Rigid and Rigid-Flex pcbs and sequential lamination build up technology. Three different processes take place in one unit; lay-up, layer to layer alignment and bonding. This process eliminates the added tolerances associated with pin lamination.

Interested in a Demo at our office? Please contact us!



FEATURES

Optical align and bond
Rigid, Flex and Rigid-
flex boards

The system will process
all panel sizes from
330mm x 356mm to
610mm x 762mm (13" x
14" to 24"x 30")

Simple touch screen
controls

Ideal for prototype,
small volume and high
mix production

MORE INFORMATION

ADEON TECHNOLOGIES

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